【ABSTRACT】

TAPE FOR PROCESSING SEMICONDUCTOR WAFER

The present invention relates to a tape for processing a semiconductor wafer including: a release film having a relatively long length; an adhesive layer formed on a first surface of the release film and having a predetermined plane shape; a pressure-sensitive adhesive film having a label portion having a predetermined plane shape and formed to cover the adhesive layer in such a manner as to be brought into contact with the release film around the adhesive layer and a surrounding portion adapted to surround the outside of the label portion; and a support member formed at the both end portions of the release film in a short direction of the release film, on a second surface of the release film opposite to the first surface of the release film on which the adhesive layer and the pressure-sensitive adhesive film are formed, the support member having a coefficient of linear expansion of 300ppm/℃ or less.